



Specifications

Electrical

Voltage Rating: 30V(DC)

Current Rating: 0.5A AC,DC (AWG#32)

0.2A AC,DC (AWG#36)

Contact Resistance: Initial value/20m Ω max

After environmental testing/40m Ω max

Dielectric Withstanding Voltage: 200V AC/1minute

Insulation Resistance: 100M Ω min

Material

Circuits: 2~20;and 22

Insulator: Polyamide, UL 94V-0

Temperature Range: -25°C~+85°C(including temperature rise in applying electrical current)

Wafer: Polyamide, UL94V-0, natural

Contact: copper alloy, tin-plated

Solder tad: Brass, tin-plated

Poles	Dimension mm (in.)		Note.
	A	B	
2	0.8(.031)	3.8(.150)	Qty./reel=2000pcs
3	1.6(.063)	4.6(.181)	
4	2.4(.094)	5.4(.213)	
5	3.2(.126)	6.2(.244)	
6	4.0(.157)	7.0(.276)	
7	4.8(.188)	7.8(.307)	
8	5.6(.220)	8.6(.339)	
9	6.4(.251)	9.4(.370)	
10	7.2(.283)	10.2(.401)	
11	8.0(.314)	11.0(.432)	
12	8.8(.346)	11.8(.463)	
13	9.6(.377)	12.6(.495)	
14	10.4(.409)	13.4(.528)	
15	11.2(.441)	14.2(.559)	
16	12.0(.472)	15.0(.591)	
17	12.8(.504)	15.8(.622)	
18	13.6(.536)	16.6(.654)	
19	14.4(.567)	17.4(.686)	
20	15.2(.598)	18.2(.717)	
22	16.8(.661)	19.8(.780)	

凱帛企業有限公司 KABO ENTERPRISE LTD.		
Name Pitch0.8mm Wire to Board Wafer SMT R/A TYPE		
Drawing No. WAFER-0.8-1002-xx93N		
DR	CHK	APPD
General Tolerances : x.xx±0.25 x.x±0.30	Unit : mm	Scale : ROM